IN THE SPECIFICATION

On page 2 line one please insert - This is a Divisional Application of

Serial No. 09/115,405 filed on July 14, 1998 which is a Divisional Application of

Serial No. 08/884,912 filed on June 30, 1997. --

IN THE CLAIMS:

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Please cancel Claims 1-29 without prejudice.

Please add the following claims.

1 30. A samiconductor device comprising:

a gate electrode formed on a gate dielectric formed on a substrate surface, the gate electrode having a first thickness;

a gate silicon germanium film formed on the gate electrode, the gate silicon germanium film having a second thickness;

a gate silicide layer formed on the gate silicon germanium film, the silicide layer having a third thickness;

a pair of sidewall spacers on opposite sides of the gate electrode, the sidewall spacers having a first height above the substrate surface, the first height greater than the sum of the first and second and third thicknesses.

31. The semiconductor device of claim 30, wherein the gate electrode is polysilicon.

32. The sericonductor device of claim 30, further comprising:

a pair of source and drain regions formed on opposite sides of the gate electrode.

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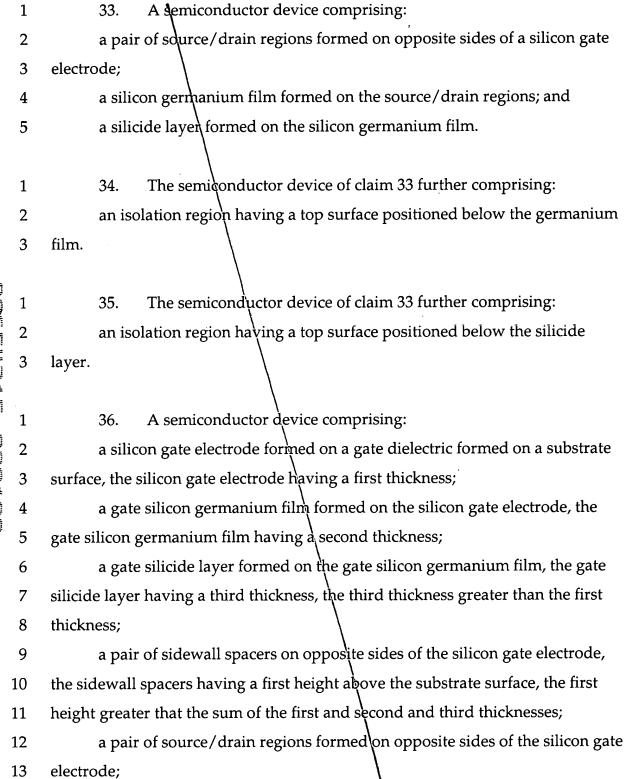
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regions; and

germanium film.



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a source/drain silicon germanium film formed on the source/drain

a source/drain silicide layer formed on the source/drain silicon



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37. The semiconductor device of claim 36 wherein the silicon

gate electrode is polyalicon.



38. A method of forming a semiconductor device comprising:

forming a gate electrode having a first thickness on a gate dielectric layer formed on a first surface of a substrate;

forming a pair of source/drain regions on opposite sides of the gate electrode;

forming a silicon germanium film having a second thickness on the gate electrode;

forming a silicon germanium film having the second thickness on the source/drain regions;

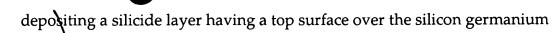
forming a silicide layer having a third thickness on the silicon germanium films.

39. The method of claim 38 further comprising:

forming a pair of sidewall spacers having a first height above the substrate surface on opposite sides of the gate electrode, wherein the first height is greater than the sum of the first and second and third thicknesses.

- 40. The method of claim 39, wherein the sidewall spacers comprise silicon nitride.
- 41. A method of forming a semiconductor device, comprising:
- forming an isolation region having a top surface in a semiconductor substrate;
- etching the semiconductor substrate adjacent to the isolation region to form a recess region;
- depositing a silicon germanium film having a top surface in the recessed region; and

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9 film.

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- 42. The method of forming a semiconductor device of claim 41, wherein the silicide layer top surface extends above the isolation region top surface.
- 1 43. The method of forming a semiconductor device of claim 42, 2 wherein the silicon germanium film top surface extends above the isolation 3 region top surface.

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